ABSTRACT

A semiconductor device in which defective resin filling can be prevented. One embodiment has a metal heat-releasing plate (103) with good thermal conductivity, which is sealed within a resin portion (107). An inner lead (101) is attached to the heat-releasing plate (103) and is at the same time provided with a bent portion. The heat-releasing plate (103) is located at the center of the resin portion (107) in its thickness-wise direction. The above arrangement roughly equalizes the spaces above and under the heat-releasing plate (103), thereby improving the resin filling performance to enable fabrication of a semiconductor device without causing defective resin filling such as an unfilled portion.